



ES1A THRU ES1J

VOLTAGE RANGE 50 to 600 Volts
CURRENT 1.0 Ampere



Features

- Fast recovery glass passivated chip
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering: 260°C/10S at terminals
- Component in accordance to ROHS 2002/95/1 and WEEE 2002/96/EC



DO-214AC (SMA)

Mechanical Data

- Case: JEDEC DO-214AC mold plastic Body over glass passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Laser band denote cathode band
- Weight: 0.0024 ounce, 0.068 gram

Maximum Ratings and Electrical Characteristics

- Ratings at 25°C ambient temperature unless otherwise specified
- Single phase, half wave, 60Hz, resistive or inductive load
- For capacitive load derate current by 20%

TYPE NUMBER	SYMBOLS	ES1A	ES1B	ES1C	ES1D	ES1F	ES1G	ES1J	UNIT
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	Volts
Maximum RMS Voltage	V_{RMS}	35	70	105	140	210	280	420	Volts
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	Volts
Maximum Average Forward Rectified Current At $T_A=125^\circ\text{C}$	$I_{(AV)}$	1.0							Amps
Peak Forward Surge Current 8.3ms single half sine wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							Amps
Maximum Instantaneous Forward Voltage at 1.0A	V_F	0.95			1.25		1.70		Volts
Maximum DC Reverse Current at rated DC blocking voltage at	$T_A = 25^\circ\text{C}$	5.0							μAmps
	$T_A = 125^\circ\text{C}$	100							
Maximum Reverse Recovery Time (NOTE 3)	T_{RR}	35							nS
Typical Junction Capacitance (NOTE 2)	C_J	10			8				pF
Typical Thermal Resistance (NOTE 1)	$R_{\theta JA}$	85							$^\circ\text{C/W}$
	$R_{\theta JL}$	35							
Operating Junction Temperature	T_J	(-55 to +175)							$^\circ\text{C}$
Storage Temperature Range	T_{STG}	(-55 to +175)							$^\circ\text{C}$

Notes:

1. Thermal resistance from Junction to ambient and from junction to lead mounted on PCB. with 0.2×0.2"(5.0 × 5.0mm) copper pad areas.
2. Measured at 1.0MHz and applied reverse voltage of 4.0V.
3. Reverse Recovery Test Conditions: $I_f=0.5A, I_r=1.0A, I_{rr}=0.25A$.



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Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

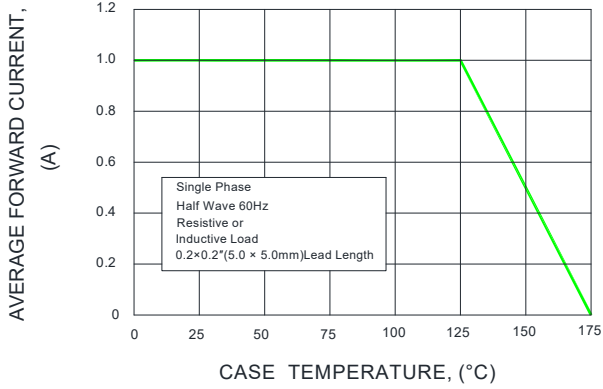


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

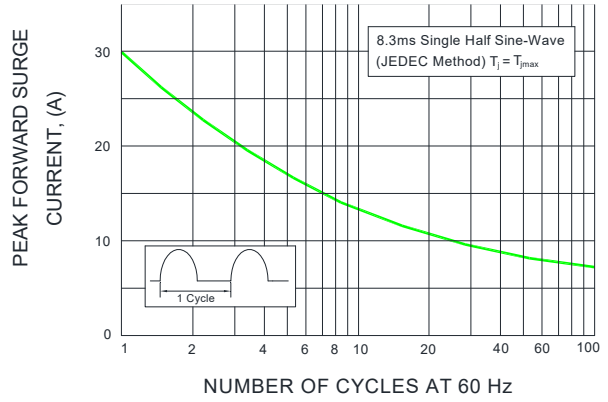


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

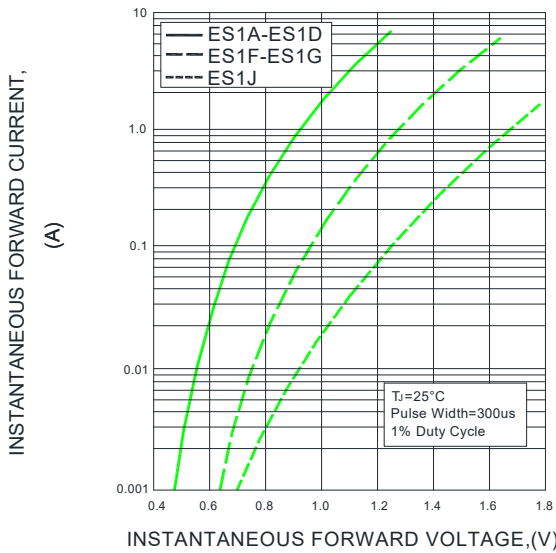


FIG.4-TYPICAL REVERSE CHARACTERISTICS

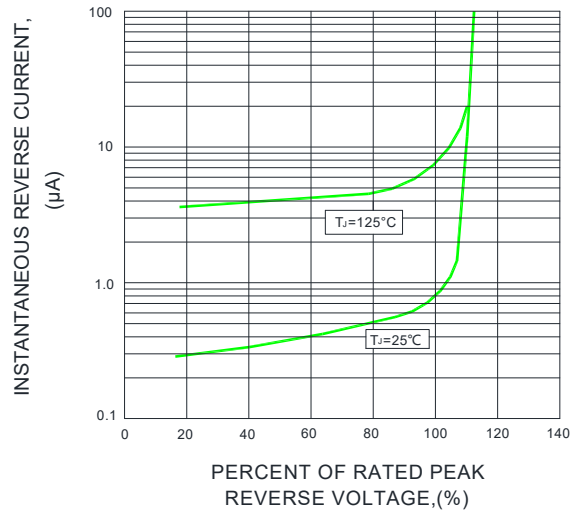


FIG.5-TYPICAL JUNCTION CAPACITANCE

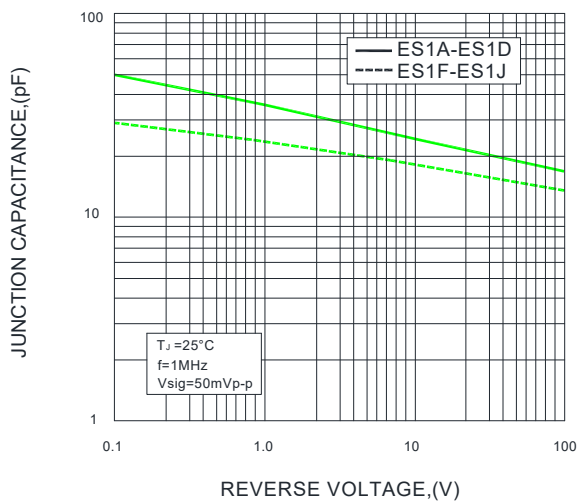
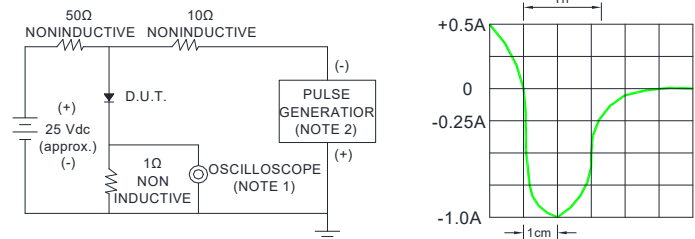


FIG.6-TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTES : 1.Rise Time=7ns max. Input Impedance= 1 magohm. 22pF
2.Rise time=10ns max. Source Impedance= 50 ohms

SET TIME BASE FOR 50/100ns/cm

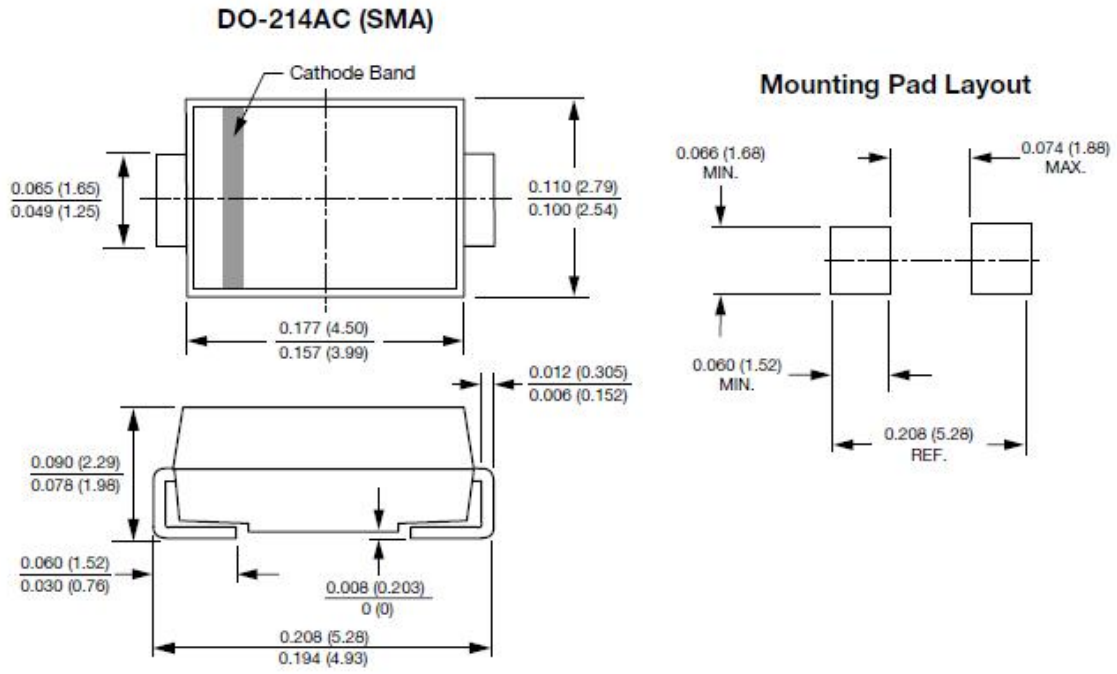


SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

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Package Outline Dimensions in inches (millimeters)



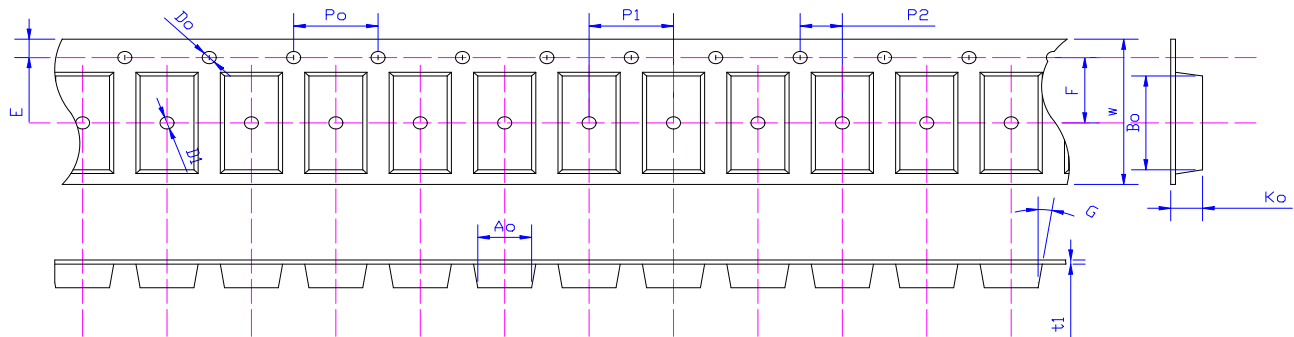


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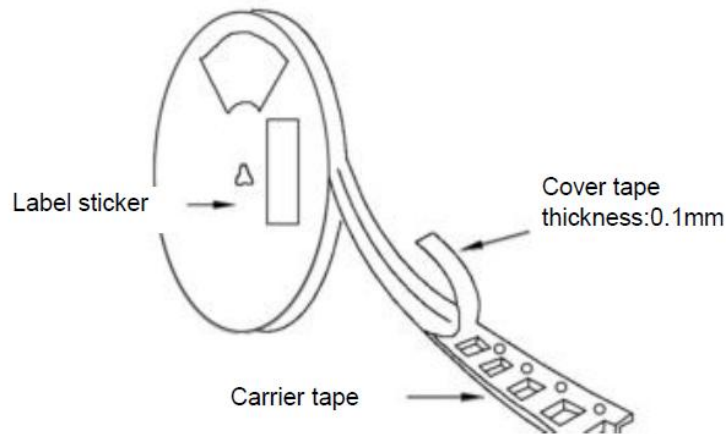
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Package Reel Information



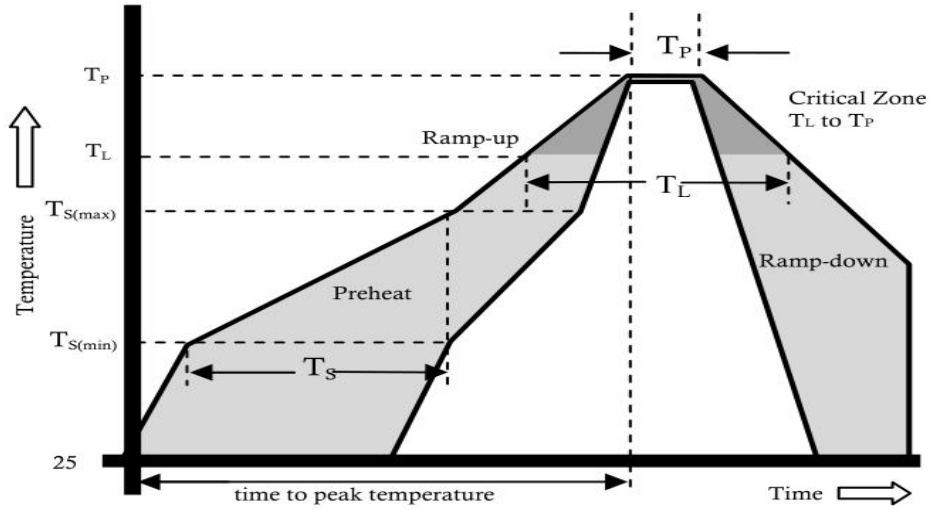
Specifications	Ao	Bo	Ko	Po	W	t1
SMA	2.55±0.10	5.10±0.10	2.36±0.10	4.00±0.1	12.0±0.05	0.23±0.02



DEVICE TYPE	Tape Width	13"Reel			07"Reel			
		Q'TY/REEL(pcs)	BOX/CARTON	Q'TY/CARTON(pcs)	Q'TY/REEL(pcs)	REEL/BOX	BOX/CARTON	Q'TY/CARTON(pcs)
SMA	12mm	5000	8	80000	1500	2	16	48000



Reflow Profile



Reflow Condition		Pb-Free Assembly
Pre Heat	Temperature Min.	+150°C
	Temperature Max.	+200°C
	Time(Min to Max)	60-180 secs.
Average ramp up rate(Liquidus Temp(T_L) to peak)		3°C/sec. Max.
T_S (max) to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	Temperature (T_L)(Liquidus)	+217°C
	Temperature (T_L)	60-150 secs.
Peak Temp (T_P)		+(260±0/-5)°C
Time within 5°C of actual Peak Temp (T_P)		25 secs.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to peak Temp (T_P)		8 min. Max.
Do not exceed		+260°C